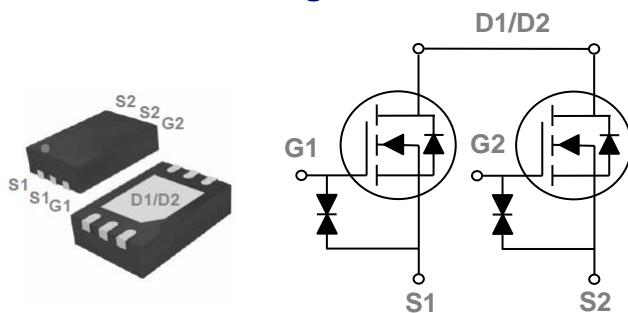


### General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

### DFN2x3 Dual Pin Configuration



BVDSS	RDSON	ID
20V	8.2mΩ	11A

### Features

- 20V,11A,  $RDS(ON) = 8.2m\Omega$  @ $VGS = 4.5V$
- Improved dv/dt capability
- Fast switching
- G-S ESD Protection Diode Embedded
- Green Device Available

### Applications

- Handheld Instruments
- POL Applications
- Battery Protection Applications

### Absolute Maximum Ratings $T_c=25^\circ C$ unless otherwise noted

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	20	V
$V_{GS}$	Gate-Source Voltage	$\pm 12$	V
$I_D$	Drain Current – Continuous ( $T_c=25^\circ C$ )	11	A
	Drain Current – Continuous ( $T_c=70^\circ C$ )	8.8	A
$I_{DM}$	Drain Current – Pulsed <sup>1</sup>	70	A
$P_D$	Power Dissipation ( $T_c=25^\circ C$ )	1.56	W
	Power Dissipation – Derate above 25°C	0.0125	W/°C
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	80	°C/W

**Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)**
**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	20	---	---	V
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =18V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C	---	---	1	uA
		V <sub>DS</sub> =16V, V <sub>GS</sub> =0V, T <sub>J</sub> =70°C	---	---	10	uA
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±12V, V <sub>DS</sub> =0V	---	---	±10	uA

**On Characteristics**

R <sub>Ds(on)</sub>	Static Drain-Source On-Resistance <sup>3</sup>	V <sub>GS</sub> =4.5V, I <sub>D</sub> =5.5A	4.5	6	8.2	mΩ
		V <sub>GS</sub> =4V, I <sub>D</sub> =5.5A	4.7	6.2	8.5	mΩ
		V <sub>GS</sub> =3.7V, I <sub>D</sub> =5.5A	5	6.5	9	mΩ
		V <sub>GS</sub> =3.1V, I <sub>D</sub> =5.5A	5.5	7	9.4	mΩ
		V <sub>GS</sub> =2.5V, I <sub>D</sub> =5.5A	6	8.2	11	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	0.5	0.72	1.5	V
gfs	Forward Transconductance	V <sub>DS</sub> =5V, I <sub>D</sub> =5.5A	---	20	---	S

**Dynamic and switching Characteristics**

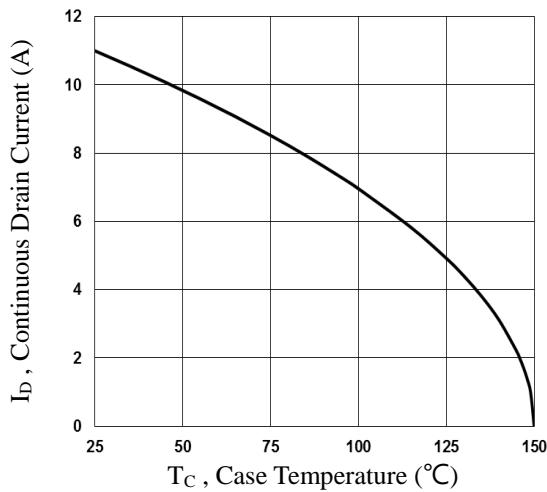
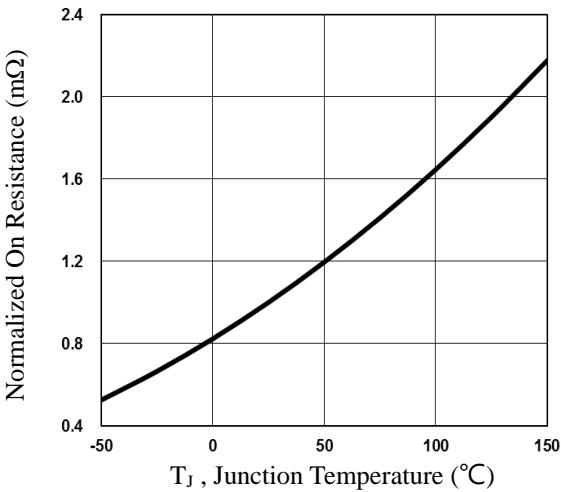
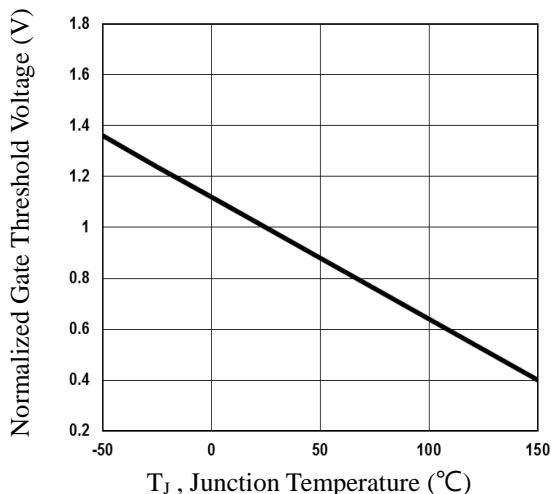
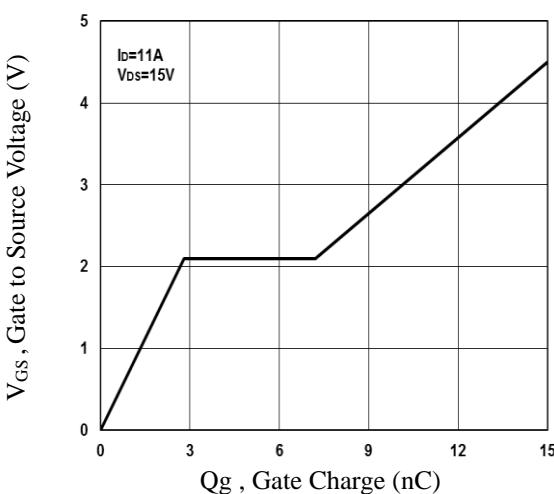
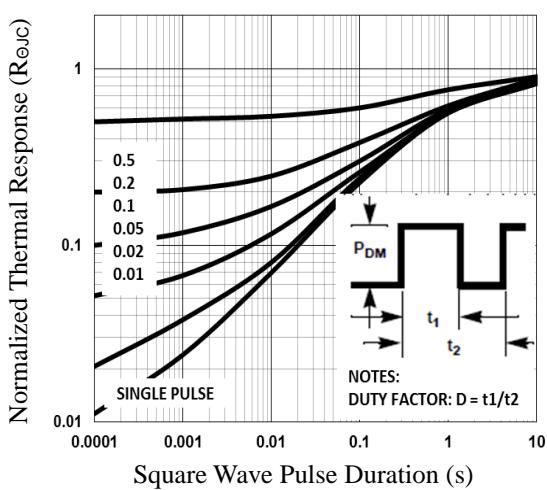
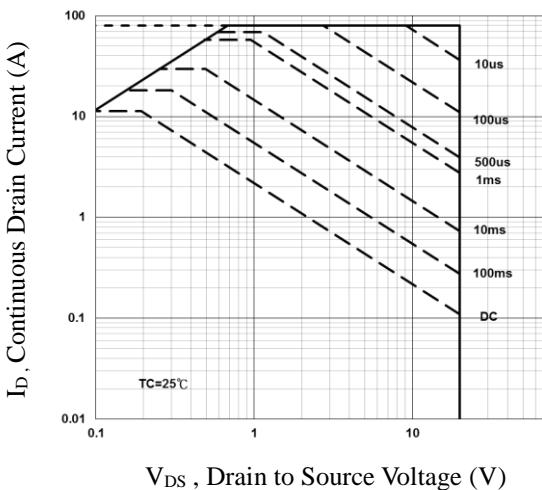
Q <sub>g</sub>	Total Gate Charge <sup>2,3</sup>	V <sub>DS</sub> =15V, V <sub>GS</sub> =4.5V, I <sub>D</sub> =11A	---	15	30	nC
Q <sub>gs</sub>	Gate-Source Charge <sup>2,3</sup>		---	2.8	5.6	
Q <sub>gd</sub>	Gate-Drain Charge <sup>2,3</sup>		---	4.4	8.8	
T <sub>d(on)</sub>	Turn-On Delay Time <sup>2,3</sup>	V <sub>DD</sub> =15V, V <sub>GS</sub> =10V, R <sub>G</sub> =6Ω I <sub>D</sub> =5.5A	---	28	56	ns
T <sub>r</sub>	Rise Time <sup>2,3</sup>		---	64	128	
T <sub>d(off)</sub>	Turn-Off Delay Time <sup>2,3</sup>		---	60	120	
T <sub>f</sub>	Fall Time <sup>2,3</sup>		---	55	110	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =10V, V <sub>GS</sub> =0V, F=1MHz	---	1350	2500	pF
C <sub>oss</sub>	Output Capacitance		---	185	350	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	160	300	

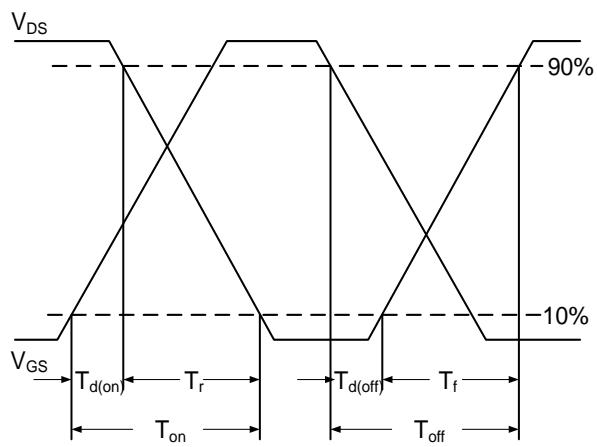
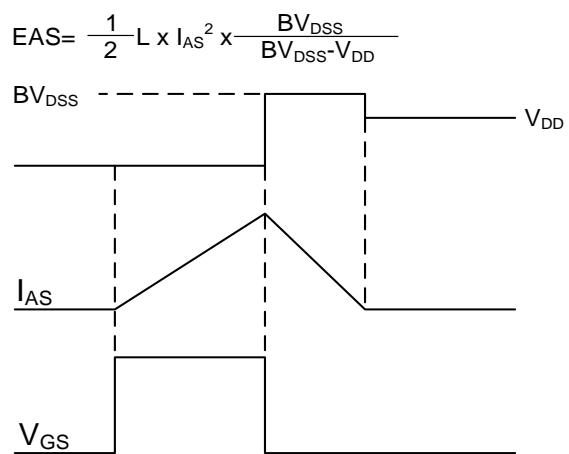
**Drain-Source Diode Characteristics and Maximum Ratings**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I <sub>s</sub>	Continuous Source Current	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current	---	---	11	A
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V, I <sub>s</sub> =1A, T <sub>J</sub> =25°C	---	---	1	V

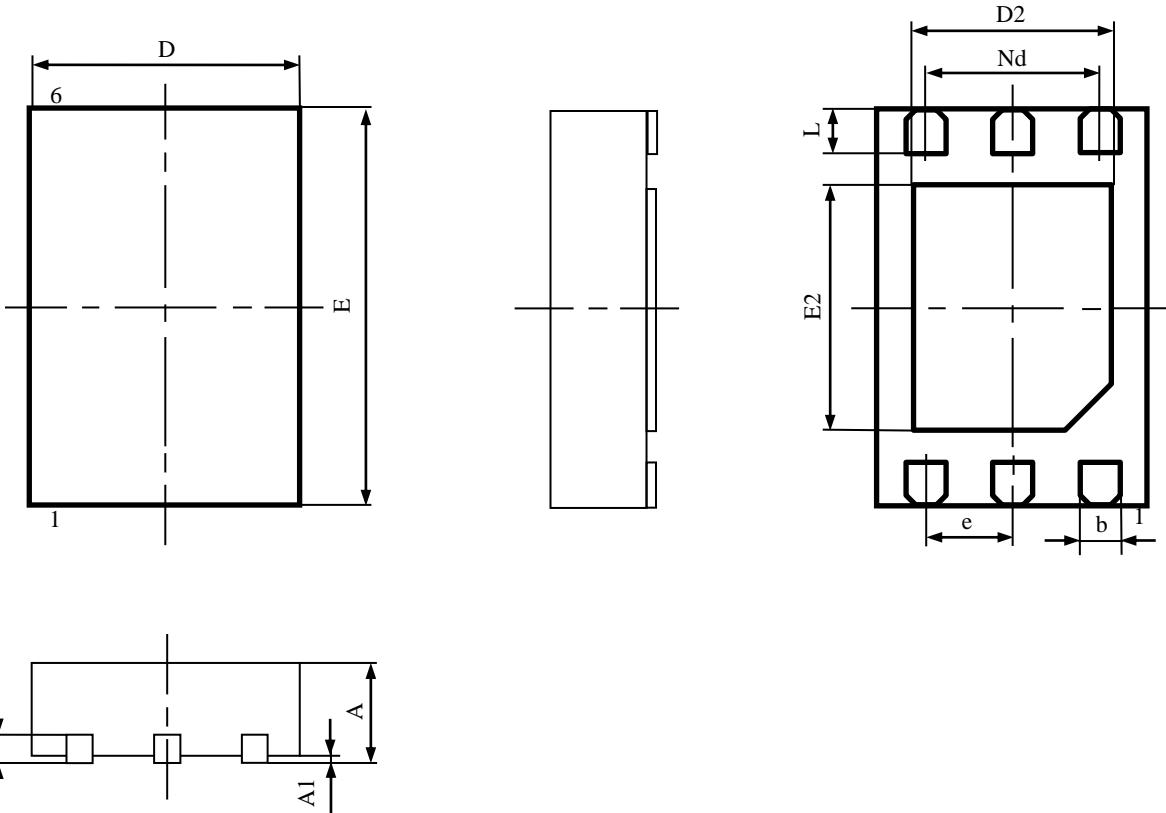
Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%.
3. Essentially independent of operating temperature.


**Fig.1 Continuous Drain Current vs. T<sub>c</sub>**

**Fig.2 Normalized RDSON vs. T<sub>j</sub>**

**Fig.3 Normalized V<sub>th</sub> vs. T<sub>j</sub>**

**Fig.4 Gate Charge Waveform**

**Fig.5 Normalized Transient Response**

**Fig.6 Maximum Safe Operation Area**


**Fig.7 Switching Time Waveform**

**Fig.8 EAS Waveform**

## DFN2X3 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	0.800	0.700	0.031	0.028
A1	0.050	0.02typ.	0.002	0.001typ.
b	0.350	0.200	0.014	0.008
c	0.250	0.180	0.010	0.007
D	2.100	1.900	0.083	0.075
D2	1.600	1.400	0.063	0.055
e	0.5BSC		0.02BSC	
Nd	1.0BSC		0.04BSC	
E	3.100	2.900	0.122	0.114
E2	1.750	1.650	0.069	0.065
L	0.400	0.300	0.016	0.012

## DFN2X3 RECOMMENDED LAND PATTERN

